



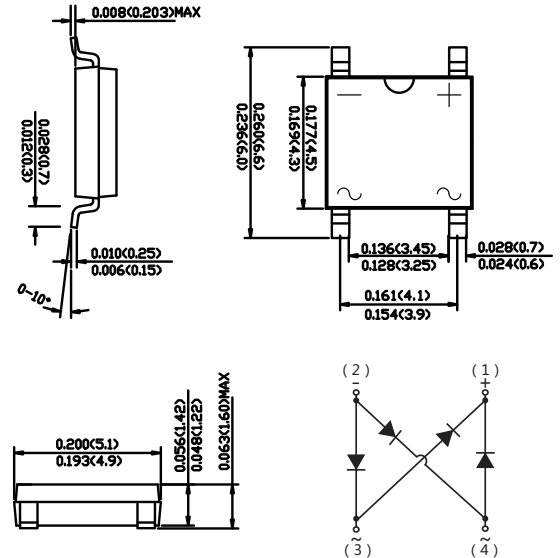
EABS2 THRU EABS8

Voltage Range - 200 to 600 V olts Current - 0.8/1.0 Ampere

GLASS PASSIVATED SUPER FAST RECOVERY BRIDGE RECTIFIERS

Features

- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic technique
- ◆ High temperature soldering guaranteed: 260°/10 seconds at 5 lbs., (2.3kg) tension
- ◆ Small size, simple installation
- ◆ High surge current capability
- ◆ Glass passivated chip junction



Mechanical Data

Case : JEDEC ABS Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.003 ounce, 0.098 grams

Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MDD EABS2	MDD EABS4	MDD EABS6	MDD EABS8	UNITS
Marking Code						
Maximum repetitive peak reverse voltage	V_{RRM}	100	200	400	600	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	V
Maximum DC blocking voltage	V_{DC}	100	200	400	600	V
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	$I_{F(AV)}$			0.8 1.0		A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}			30		A
Maximum instantaneous forward voltage drop per leg at 0.4A	V_F		0.95	1.25	1.7	V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ C$ $T_A=100^\circ C$	I_R			5 500		μA μA
Typical thermal resistance(NOTE 3)	$R_{\theta JL}$ $R_{\theta JA}$			25 75		$^\circ C/W$
Maximum reverse recovery time (NOTE 4)	t_{rr}			35		$^\circ C$
Operating temperature range	T_J			-55 to +150		$^\circ C$
storage temperature range	T_{STG}			-55 to +150		$^\circ C$

NOTES: 1. On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads.
 2. On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad.
 3. Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.
 4. Reverse recovery condition $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$.



Ratings And Characteristic Curves

FIG.1 FORWARD DERATING CURVE

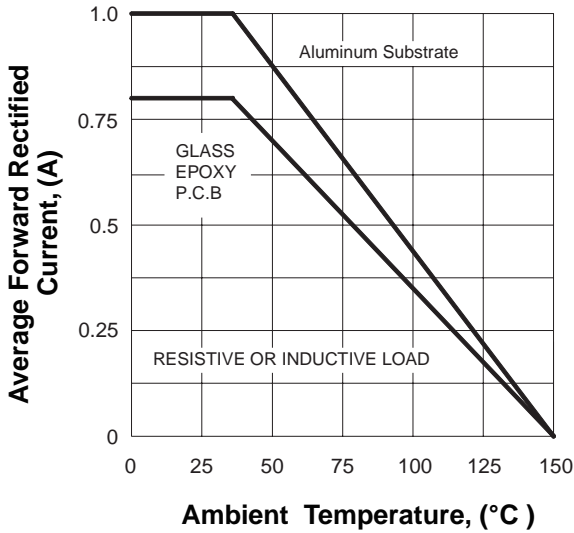


FIG.2 PEAK FORWARD SURGE CURRENT

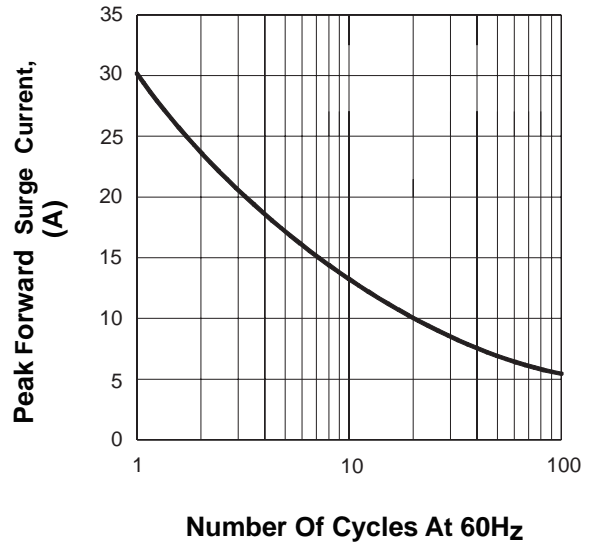


FIG.3 TYPICAL FORWARD CHARACTERISTICS

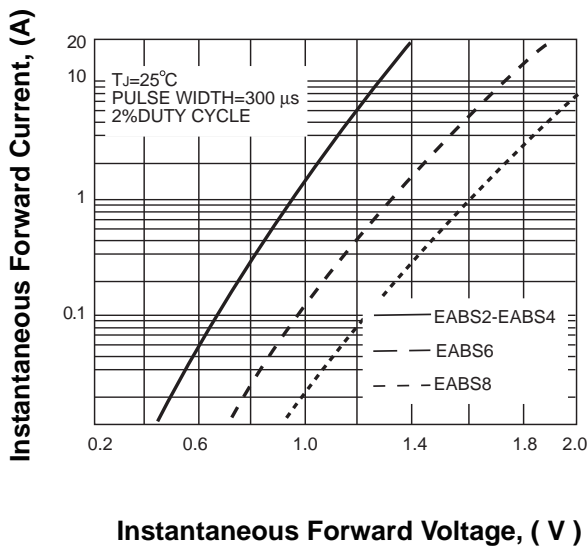
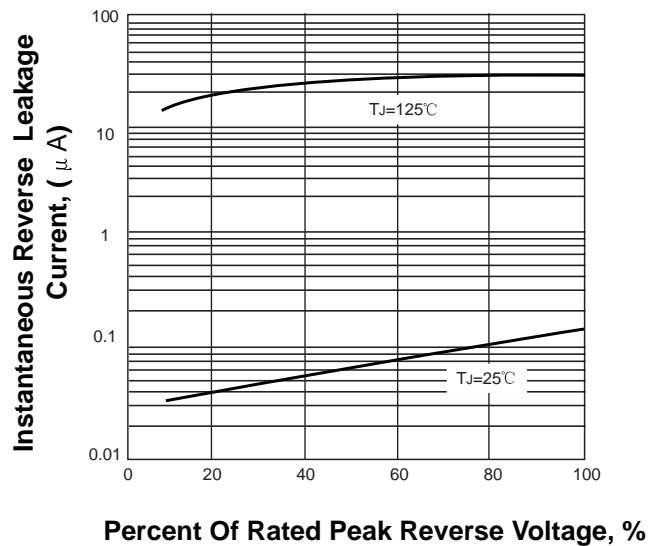


FIG.4 TYPICAL REVERSE CHARACTERISTICS



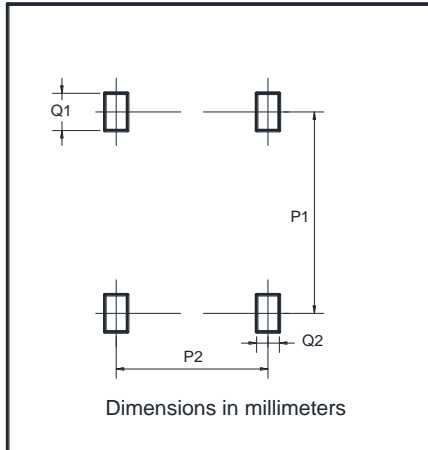
The curve above is for reference only.



EABS2 THRU EABS8

Voltage Range - 200 to 600 V olts Current - 0.8/1.0 Ampere

Suggested Pad Layout



Dim	Min
P1	5.72
P2	4.00
Q1	1.00
Q2	0.90